

General Description

The WSD2018DN22 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSD2018DN22 meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

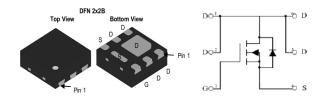
Product Summery

BVDSS	RDSON	ID
20V	$15m\Omega_{(MAX)}$	12A

Applications

- High Frequency Point-of-Load Synchronous s Small power switching for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- Load Switch

DFNWB2×2-6L-J Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter Rating		Units	
V_{DS}	Drain-Source Voltage	20	V	
V_{GS}	Gate-Source Voltage	±10	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 4.5V ¹	12	А	
I _D @T _C =70°C	Continuous Drain Current, V _{GS} @ 4.5V ¹ 10		Α	
I _{DM}	Pulsed Drain Current ² 40		А	
P _D @T _A =25°C	Total Power Dissipation ³	1.5	W	
T _{STG}	Storage Temperature Range -55 to 150		$^{\circ}$	
T _J	Operating Junction Temperature Range -55 to 150		${\mathbb C}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient ¹		167	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		65	°C/W



Electrical Characteristics (T_J=25 C, unless otherwise noted)

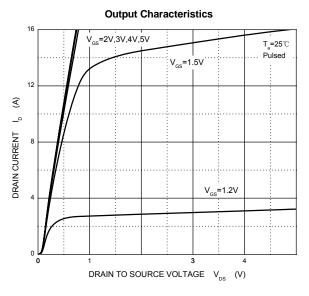
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	20			V	
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25°C , I _D =1mA		0.027		V/°C	
		V _{GS} =4.5V , I _D =5A		10	15	mΩ	
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V_{GS} =2.5 V , I_D =5 A		13	18		
		V _{GS} =1.8V , I _D =5A		18	30		
V _{GS(th)}	Gate Threshold Voltage	\/ -\/ -250\	0.4	0.7	1.0	V	
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$-V_{GS}=V_{DS}$, $I_D=250uA$		2.56		mV/℃	
	Drain Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =25°C			1		
I _{DSS}	Drain-Source Leakage Current	V _{DS} =16V , V _{GS} =0V , T _J =55°C			5	uA	
I _{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 12V$, $V_{DS}=0V$			±100	nA	
gfs	Forward Transconductance	V_{DS} =4V , I_D =9.7A	20			S	
Rg	Gate Resistance	f=1MHz		2.5		Ω	
Q_g	Total Gate Charge (4.5V)				32		
Q_gs	Gate-Source Charge	V_{DS} =4V , V_{GS} =5V , I_{D} =10A		2.5		nC	
Q _{gd}	Gate-Drain Charge			6.5			
T _{d(on)}	Turn-On Delay Time			12	20		
Tr	Rise Time	V_{DD} =4 V , V_{GS} =4.5 V , R_{G} =1 Ω		10	25	no	
$T_{d(off)}$	Turn-Off Delay Time	I_D =10A ,RL=0.4 Ω		65	70	ns	
T _f	Fall Time			20	60		
C _{iss}	Input Capacitance			1800			
C _{oss}	Output Capacitance	V _{DS} =4V , V _{GS} =0V , f=1MHz		650		pF	
C _{rss}	Reverse Transfer Capacitance			450			

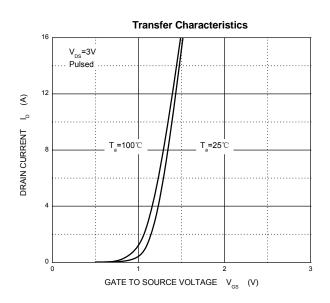
Notes:

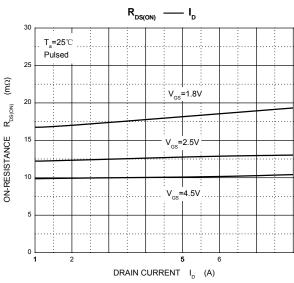
- 1.Surface mounted on FR4 board using 1 square inch pad size,1oz copper.
- 2. Surface mounted on FR4 board using the minimum pad size, 1oz copper.
- 3. Pulse test : Pulse width=300µs, duty cycle≤2%.
- 4. These parameters have no way to verify.

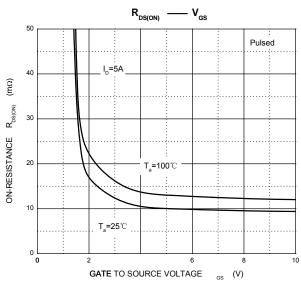


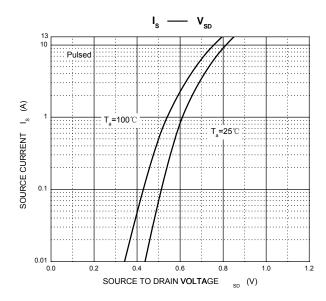
Typical Characteristics

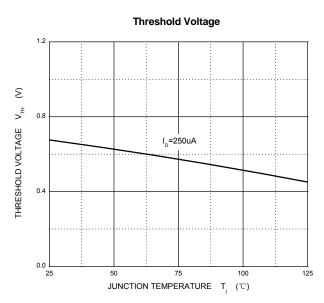






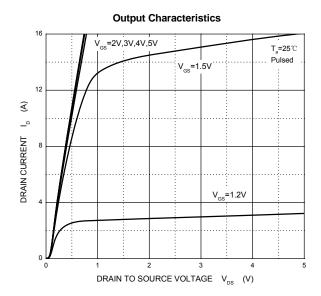


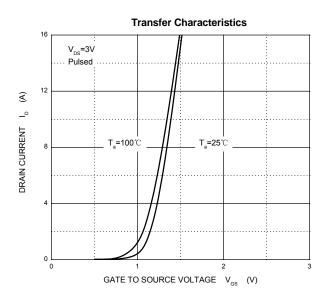


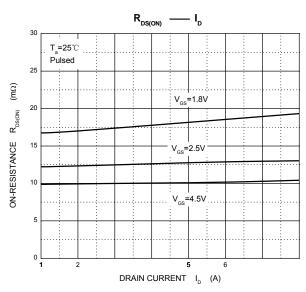


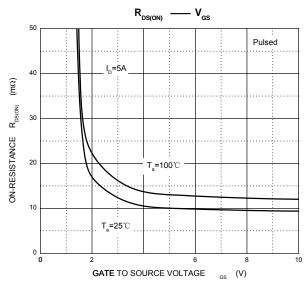


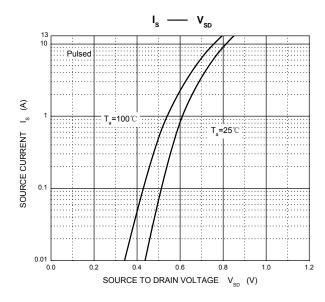


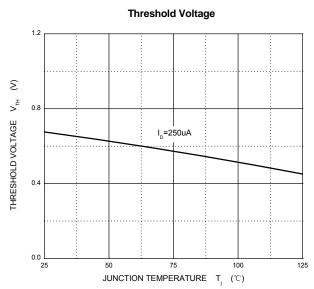






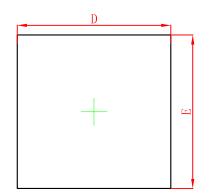


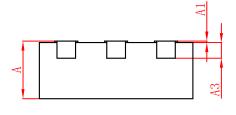


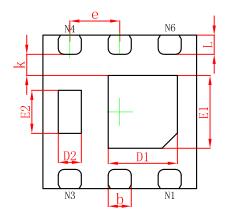




DFNWB2X2-6L-J Package Outline Dimensions

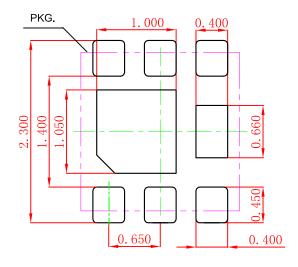






Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
Α	0.700	0.800		0.032	
A1	0.000	0.050	0.000	0.002	
A3	0.203REF.		0.008REF.		
D	1.924	2.076	0.076	0.082	
E	1.924	2.076	0.076	0.082	
D1	0.800	1.000	0.031	0.039	
E1	0.850	1.050	0.033	0.041	
D2	0.200	0.400	0.008	0.016	
E2	0.460	0.660	0.018	0.026	
k	0.200MIN.		0.008MIN.		
b	0.250	0.350	0.010	0.014	
е	0.650TYP.		0.026	TYP.	
L	0.174	0.326	0.007	0.013	

DFNWB2X2-6L-J Suggested Pad Layout



Note:

- 1. Controlling dimension:in millimeters.
- 2.General tolerance:± 0.050mm.
- 3. The pad layout is for reference purposes only.



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